Information about *Dow Corning*[®] brand Silicone Encapsulants

Silicones and Electronics

Long-term, reliable protection of sensitive circuits and components is becoming more important in many of today's delicate and demanding electronic applications. Silicones function as durable dielectric insulation, as barriers against environmental contaminants and as stress-relieving shock and vibration absorbers over a wide temperature and humidity range.

In addition to sustaining their physical and electrical properties over a broad range of operating conditions, silicones are resistant to ozone and ultraviolet degradation, have good chemical stability and are available in a variety of useful forms as conformal coatings, encapsulants and adhesives. Dow Corning's broad range of general purpose and specialty products offers you a choice of materials for your application needs.

DESCRIPTION

Dow Corning[®] silicone encapsulants are supplied as two-part liquid component kits comprised of:

| Mix Ratio | Components |
|------------------------------|----------------------|
| <u>(by weight or volume)</u> | <u>(as supplied)</u> |
| 1:1 | Part A/Part B |
| 10:1 | Base/Curing agent |

When liquid components are thoroughly mixed, the mixture cures to a flexible elastomer, which is suited for the protection of electrical/electronic applications. *Dow Corning* silicone encapsulants cure without exotherm at a constant rate regardless of sectional thickness or degree of confinement. *Dow Corning* silicone elastomers require no post cure and can be placed in service immediately following the completion of the cure schedule with an operating temperature range of -45 to 200°C (-49 to 392°F). Select materials have been classified by Underwriters Laboratories and/or meet military specifications. Standard silicone encapsulants require a surface treatment with a primer in addition to good cleaning for adhesion while primerless silicone encapsulants require only good cleaning.

Two-Part Silicone Elastomers

Type Elastomers

Physical Form Two-part silicone elastomers

Special Properties

Flowable liquid; cures to flexible elastomer; constant cure rate, regardless of sectional thickness or degree of confinement; service range of -45 to 200°C (-49 to 392°F); no post cure required

Potential Uses

Protection of electrical/electronic devices

DOW CORNING

PRODUCT INFORMATION

| Product | Description | Features |
|---|--|---|
| Silicone Encapsulants | 1 | |
| Sylgard [®] 160 Silicone Elastomer | Low cost; good thermal conductivity | Two part; 1:1 mix; RT/HA cure; minimal shrinkage; no exotherm during cure; no solvents or cure byproducts; repairable; good dielectric properties; deep section cure; flexible elastomer |
| Sylgard® 165 Silicone Elastomer | Fast cure; low cost; good thermal conductivity | |
| Sylgard® 170 Silicone Elastomer | Low viscosity | |
| Sylgard [®] 170 Fast Cure Silicone Elastomer | Fast cure; low viscosity | |
| <i>Dow Corning</i> [®] 96-082 A & B Encapsulant | Very low viscosity; flame retardant; nonmelting; self- extinguishing; extremely long pot life; wide temperature range | |
| <i>Sylgard</i> [®] 182 Silicone Elastomer | Transparent; long pot life; heat cure | Two part; 10:1 mix; minimal shrinkage; no exotherm during cure; no solvents or cure byproducts; deep section cure; repairable; good dielectric properties; flexible elastomer |
| Sylgard [®] 184 Silicone Elastomer | Transparent; RT/HA cure | |
| Sylgard [®] 186 Silicone Elastomer | Clear; RT/HA cure; high tear strength | |
| Dow Corning [®] 3-6121 Encapsulating Elastomer | Low-temperature performance below -65°C (-85°F); clear; high tear and tensile strength; RT/HA cure; high refractive index | |
| Primerless Silicone Encapsula | ints | |
| Dow Corning® 3-8264 Primerless Silicone Adhesive | Excellent unprimed adhesion; heat cure; elastomeric | Two part; 1:1 mix; heat cure; minimal shrinkage; no exotherm during cure; no solvents or cure byproducts; repairable; good dielectric properties |
| Dow Corning [®] 567 Primerless Silicone Encapsulant | Heat cure; unprimed adhesion; elastomeric | |
| Two-Part Room-Temperature | Condensation-Cure Encapsulants | <u> </u> |
| <i>Dow Corning®</i> 255 Primerless Elastomer | Rapid room temperature and deep-section cure; self-priming adhesion; good room-temperature adhesion to most substrates; adhesion increases with time | Two part; 10:1 mix; noncorrosive; good dielectric properties; flexible elastomer; non-heat curable; refrigerate curing agent for maximum shelf life; tin catalyst cannot be inhibited; reversion possible with heat and pressure in sealed environments |

| Product | Potential Uses | Application Methods | Cure ^{1,2} | | | |
|---|--|--|---|--|--|--|
| Silicone Encapsulants | • | | 1 | | | |
| Sylgard [®] 160 Silicone Elastomer | General potting applications: power supplies, connectors, sensors, industrial controls, transformers, amplifiers, high voltage resistor packs, relays | Supplied as two-part liquid component kits comprised of Part A/Part B to be mixed in a 1:1 ratio by weight or volume; automated mixing and dispensing; manual mixing | 24 hours at 25°C (77°F) 10 minutes at 100°C (212°F) 5 minutes at 150°C (302°F) | | | |
| <i>Sylgard</i> [®] 165 Silicone Elastomer | | Supplied as two-part liquid component kits comprised of Part A/Part B to be mixed in a 1:1 ratio by weight or volume; automated mixing and dispensing | 5 minutes at 25°C (77°F) | | | |
| <i>Sylgard</i> [®] 170 Silicone Elastomer | | Supplied as two-part liquid component kits comprised of Part A/Part B to be mixed in a 1:1 ratio by weight or volume; automated mixing and dispensing; manual mixing | | | | |
| <i>Sylgard</i> [®] 170 Fast Cure Silicone Elastomer | | Supplied as two-part liquid component kits comprised of Part A/Part B to be mixed in a 1:1 ratio by weight or volume; automated mixing and dispensing | 10 minutes at 25°C (77°F) | | | |
| <i>Dow Corning®</i> 96-082 A & B Encapsulant | Applications requiring the thorough impregnation possible only with a very low viscosity resin | Supplied as two-part liquid component kits comprised of Part A/Part B to be mixed in a 1:1 ratio by weight or volume; automated mixing and dispensing; manual mixing | 30 minutes at 150°C (302°F) | | | |
| Sylgard [®] 182 Silicone Elastomer | General potting applications: power supplies, connectors, sensors, industrial controls, transformers, amplifiers, high voltage resistor | Supplied as two-part liquid component kits comprised of Base/Curing Agent to be mixed in a 10:1 ratio by weight or volume; automated mixing and dispensing; manual mixing | 45 minutes at 100°C (212°F) 20 minutes at 125°C (257°F) 10 minutes at 150°C (302°F) | | | |
| <i>Sylgard</i> [®] 184 Silicone Elastomer | packs, relays; adhesive/encapsulant for solar cells; adhesive handling beam lead integrated circuits during processing | ~48 hours at room temp 45 minutes at 100°C (212°F) 20 minutes at 125°C (257°F) 10 minutes at 150°C (302°F) | | | | |
| Sylgard [®] 186 Silicone Elastomer | | | ~48 hours at room temp 30 minutes at 100°C (212°F) 15 minutes at 150°C (302°F) | | | |
| Dow Corning [®] 3-6121 Encapsulating Elastomer | Low-temperature encapsulating applications; optical applications requiring high refractive index | | ~48 hours at room temp 20 minutes at 100°C (212°F) 10 minutes at 150°C (302°F) | | | |
| Primerless Silicone Enc | apsulants | | | | | |
| Dow Corning® 3-8264 Primerless Silicone Adhesive | Encapsulating applications requiring good primerless adhesion and lower heat cure temperatures | Supplied as two-part liquid component kits comprised of Part A/Part B to be mixed in a 1:1 ratio by weight or volume; automated or manual mixing and dispensing can be used | 150 minutes at 70°C (158°F) 30 minutes at 115°C (239°F) | | | |
| Dow Corning® 567 Primerless Silicone Encapsulant | Low cost primerless adhesion encapsulation applications | Supplied as two-part liquid component kits comprised of Part A/Part B to be mixed in a 1:1 ratio by weight or volume; automated or manual mixing and dispensing can be used | 90 minutes at 100°C (212°F) 60 minutes at 125°C (257°F) 15 minutes at 150°C (302°F) | | | |
| Two-Part Room-Tempe | rature Condensation-Cure Encapsulants | | | | | |
| Dow Corning® 255 Primerless Elastomer | General potting applications: power supplies, connectors, sensors, industrial controls, transformers, amplifiers, high voltage resistor packs, relays | Supplied as two-part liquid component kits comprised of Base/Curing Agent to be mixed in a 10:1 ratio by weight or volume; automated mixing and dispensing; manual mixing | ~4 hours at room temp 24 hours for adhesion | | | |
| | | | | | | |

¹These data were collected on 50-100 gram samples of a lot believed to be typical and should be used as initial estimates of cure times. Times will vary slightly from batch to batch and can be longer or shorter due to thermal mass of your parts and your heating ramp rate. Pretesting is recommended to confirm adequate cure for your application.

²For primerless adhesion products, cure time is based on time to reach durometer. Full adhesion may take more time at the cure temperature.

TYPICAL PROPERTIES

Specification Writers: Please contact your local Dow Corning sales office or your Global Dow Corning Connection before writing specifications on this product.

| | | | | | | | Unprimed Adhesion, Lap Shear | | | Thermal Conductivity | | ů, | sq |
|--|--|--------------------------|-----------------------------------|--------------------|------------------|--------------------|------------------------------------|-----|---------------------|-------------------------|----------------------------|---|--|
| Product | Mix Ratio | Color | Viscosity, centipoise or mPa·s | Durometer, Shore A | Specific Gravity | Working Time at RT | psi | MPa | kgf/cm ² | Watt/meter-°K | cal/cm·sec °C | Linear Coefficient of Thermal Expansion, µm/m-°C or ppm | Shelf Life from Date of Manufacture at Room Temp, months |
| Silicone Encapsulants | | • | | | | | | - | • | • | | • | |
| Sylgard [®] 160 Silicone Elastomer | 1:1 | Gray | 4000 | 60 | 1.57 | 30 min | NA | NA | NA | 0.58 | 1.4 x 10 ⁻³ | 240 | 18 |
| Sylgard [®] 165 Silicone Elastomer | 1:1 | Gray | 5000 | 52 | 1.57 | <2 min | NA | NA | NA | 0.58 | 1.4 x 10 ⁻³ | 230 | 18 |
| Sylgard [®] 170 Silicone Elastomer | 1:1 | Dark gray to black | 2900 | 40 | 1.37 | 15 min | NA | NA | NA | 0.40 | 9.6 x 10 ⁻⁴ | 270 | 24 |
| <i>Sylgard</i> [®] 170 Fast Cure Silicone Elastomer | 1:1 | Dark gray to black | 2850 | 42 | 1.37 | <5 min | NA | NA | NA | 0.40 | 9.6 x 10 ⁻⁴ | _ | 18 |
| Dow Corning [®] 96-082 A & B Encapsulant | 1:1 | Black | 1100 | 31 | 1.21 | 14 days | NA | NA | NA | 0.30 | 7.2 x 10 ⁻⁴ | 285 | 12 |
| Sylgard [®] 182 Silicone Elastomer | 10:1 | Clear | 3900 | 50 | 1.03 | >8 hours | NA | NA | NA | 0.18 | 4.3 x 10 ⁻⁴ | 310 | 24 |
| Sylgard [®] 184 Silicone Elastomer | 10:1 | Clear | 3900 | 50 | 1.03 | >2 hours | NA | NA | NA | 0.18 | 4.3 x 10 ⁻⁴ | 310 | 24 |
| Sylgard [®] 186 Silicone Elastomer | 10:1 | Trans- lucent | 65,000 | 24 | 1.12 | 2 hours | NA | NA | NA | 0.2 | 4.8 x 10 ⁻⁴ | 330 | 12 |
| <i>Dow Corning</i> [®] 3-6121 Encapsulating Elastomer | 10:1 | Trans- lucent | 25,000 | 30 | 1.13 | 2 hours | NA | NA | NA | 0.18 | 4.3 x 10 ⁻⁴ | 290 | 18 |
| Primerless Silicone Encap | sulants | | | | | | | | | | | | |
| Dow Corning® 3-8264 Primerless Silicone Adhesive | 1:1 | Black | 2900 | 45 | 1.32 | 5 hours | 385 | 2.6 | 27.0 | 0.35 | 8.4 x 10 ⁻⁴ | 290 | 9 |
| Dow Corning [®] 567 Primerless Silicone Encapsulant | 1:1 | Black | 1500 | 45 | 1.24 | >3 days | 140 | 1.0 | 9.8 | 0.30 | 7.2 x 10 ⁻⁴ | 300 | 24 |
| Two-Part Room-Tempera | Two-Part Room-Temperature Condensation-Cure Encapsulants | | | | | | | | | | | | |
| Dow Corning [®] 255 Primerless Elastomer | 10:1 | Gray to black | 5500 | 25 | 1.3 | <5 min | 44 | 0.3 | 20 | 0.26 | 6.25 x 10 ⁻⁶ | 311 | |

| | UL L | isting | Military S _l | pecification | Dielectric Strength | | | | | | |
|---|--|---|----------------------------------|-----------------------------|------------------------|-------|----------------------------------|-----------------------------------|-------------------------------|---------------------------------|----------------------------------|
| Product | Flammability Classification | UL Temperature Index, Electrical/ Mechnical, °C | Specification | Type, Class, Group | volts/mil | kV/mm | Dielectric Constant at 100 Hz | Dielectric Constant at 100 kHz | Volume Resistivity, ohm-cm | Dissipation Factor at 100 Hz | Dissipation Factor at 100 kHz |
| Silicone Encapsulants | | | | | | | | | | | |
| Sylgard [®] 160 Silicone Elastomer | 94 V-0 | 105/105 | NA | NA | 530 | 20.9 | 3.30 | 3.20 | 1.0 x 10 ¹⁵ | 0.01 | 0.002 |
| Sylgard [®] 165 Silicone Elastomer | 94 V-0 | 105/105 | NA | NA | 530 | 20.9 | 3.30 | 3.20 | 1.0 x 10 ¹⁵ | 0.01 | 0.002 |
| Sylgard [®] 170 Silicone Elastomer | 94 V-0 | 170/170 | MIL-PRF- 23586F (Grade B2) | Type I, Class II, QPL | 480 | 18.9 | 3.17 | 3.16 | 3.1 x 10 ¹³ | 0.003 | <0.001 |
| <i>Sylgard</i> [®] 170 Fast Cure Silicone Elastomer | 94 V-0 | 170/170 | NA | NA | 530 | 20.9 | 2.97 | 2.90 | 1.4 x 10 ¹⁵ | 0.005 | <0.001 |
| Dow Corning [®] 96-082 A & B Encapsulant | 94 V-0 | 170/170 | NA | NA | 500 | 19.7 | 3.14 | 3.12 | 9.5 x 10 ¹⁴ | 0.0055 | <0.001 |
| Sylgard [®] 182 Silicone Elastomer | 94 V-1 | 130/130 | MIL-I- 81550C | Type II, QPL | 540 | 21.2 | 2.65 | 2.65 | 1.2 x 10 ¹⁴ | 0.0005 | <0.001 |
| Sylgard [®] 184 Silicone Elastomer | 94 V-1 | 130/130 | MIL-I- 81550C | Type I, QPL | 540 | 21.2 | 2.65 | 2.65 | 1.2 x 10 ¹⁴ | 0.0005 | <0.001 |
| Sylgard [®] 186 Silicone Elastomer | 94 HB | 140/140 | NA | NA | 450 | 17.7 | 2.93 | 2.87 | 1.1 x 10 ¹⁴ | 0.0012 | <0.001 |
| <i>Dow Corning</i> [®] 3-6121 Encapsulating Elastomer | NA | NA | NA | NA | 415 | 16.3 | 2.92 | 2.92 | 1.4 x 10 ¹⁴ | 0.01 | <0.001 |
| Primerless Silicone Encap | Primerless Silicone Encapsulants | | | | | | | | | | |
| Dow Corning® 3-8264 Primerless Silicone Adhesive | NA | NA | NA | NA | 545 | 21.4 | 3.11 | 3.05 | 3.5 x 10 ¹⁴ | 0.007 | <0.001 |
| Dow Corning® 567 Primerless Silicone Encapsulant | 94 V-0 | 105/105 | MIL-PRF- 23586F (Grade B2) | Type I, Class IV, QPL | 520 | 20.5 | 2.85 | 2.79 | 1.0 x 10 ¹⁴ | 0.008 | 0.002 |
| Two-Part Room-Tempera | Two-Part Room-Temperature Condensation-Cure Encapsulants | | | | | | | | | | |
| Dow Corning [®] 255 Primerless Elastomer | | | | | 564 | 25 | 2.95 | 2.83 | 1.1 x 10 ¹⁵ | 0.017 | <0.0059 |

PRIMER SELECTION GUIDE

Specification Writers: Please contact your local Dow Corning sales office or your Global Dow Corning Connection before writing specifications on this product.

| <i>Dow Corning[®]</i> brand Primer or Adhesion Promoter | Flash Point, °C (°F) | Volatile Organic Content (VOC), grams/liter ⁴ | Special Properties | For Use On | For Use With | Silicone Product Examples | |
|---|----------------------------|--|---------------------|---------------------------------------|-------------------------------|------------------------------|--|
| P5200 Clear ¹ | 32 (90) | 110/705 | | | | | |
| 1200 Clear | 17 (63) | 748 | | Most metals, glass, ceramics and some | Pigmented two-part | 160, 165, 170 | |
| 1200 Red | 17 (63) | 774 | Colored for easier | plastics | addition cure | | |
| P5200 Red ² | 32 (90) | 110/705 | identification | | | | |
| 1204 | 15 (59) | 774 | | Most metals, glass | All one-part alcohol | | |
| P5204 ³ | 18 (64) | 205/591 | | and ceramics | cure | 3140, 3145, 838, 3-1753 | |
| 1205 | 5 (41) | 861 | Film-forming | Most plastics | All | | |
| 3-6060 | 37 (99) | 780 | Improves inhibition | Most plastics and metals | | 182, 184, 186 | |
| 92-023 | -4 (25) | 678 | resistance | | All two-part addition cure | | |
| <i>Sylgard</i> [®] Prime Coat | -3 (27) | 687 | | Most metals, glass and ceramics | | | |

¹P5200 Clear is a low-VOC alternative to 1200 Clear.

²P5200 Red is a low-VOC alternative to 1200 Red.

³P5204 is a low-VOC alternative to 1204.

⁴The lower VOC value is for states and air quality management districts that have recognized volatile methylsiloxanes as VOC exempt.

MIXING - 1:1/PART A:PART B

Dow Corning silicone 1:1 encapsulants are supplied in two parts that do not require lot matching. The 1:1 mix ratio, by weight or volume, simplifies the proportioning process. To ensure uniform distribution of filler, Parts A and B must each be thoroughly mixed prior to their combination in a 1:1 ratio. When thoroughly blended, the Part A and B liquid mixture should have a uniform appearance. The presence of lightcolored streaks or marbling indicates inadequate mixing and will result in incomplete cure.

Due to the fast-curing characteristics of some encapsulants included in this data sheet, automated mix and dispense equipment should be utilized. In applications sensitive to air entrapment, deairing with 28 to 30 inches Hg vacuum is required.

MIXING - 10:1/BASE:CURING AGENT

Dow Corning silicone 10:1 encapsulants are supplied in two parts as lot-matched base and curing agent that are mixed in a ratio of 10 parts base to one part curing agent, by weight. After thoroughly mixing base and curing agent, agitate gently to reduce the amount of air introduced. Allowing the mixture to set for 30 minutes before pouring may be adequate for removal of the air introduced during mixing. If air bubbles are still present, vacuum deairing may be required. Deair in a container with at least four times the liquid volume to allow for expansion of material. Air entrapped in the mixture can be removed by using a vacuum of 28 to 30 inches Hg. Continue the vacuum until the liquid expands and settles to its original volume and bubbling subsides. This may take 15 minutes to 2 hours depending on the amount of air introduced during stirring. For best curing results, glassware and glass or metal stirring implements should be used. Mix with a smooth action that does not introduce excess air.

POT LIFE/WORKING TIME

Cure reaction begins with the mixing process. Initially, cure is evidenced by a gradual increase in viscosity, followed by gelation and conversion to a solid elastomer. Pot life is defined as the time required for viscosity to double after Parts A and B (base and curing agent) are mixed. Please refer to individual pot life for each silicone encapsulant.

PROCESSING AND CURING

Thoroughly mixed *Dow Corning* silicone encapsulant may be poured/dispensed directly into the container in which it is to be cured. Care should be taken to minimize air entrapment. When practical, pouring/dispensing should be done under vacuum, particularly if the component being potted or encapsulated has many small voids. If this technique cannot be used, the unit should be evacuated after the silicone encapsulant has been poured/dispensed.

Dow Corning silicone encapsulants may be either room temperature $(25^{\circ}C/77^{\circ}F)$ or heat cured. Room temperature cure encapsulants may also be heat accelerated for faster cure. Ideal

cure conditions for each product are given in the product selection table. Two-part condensation cure encapsulants should not be heat accelerated above 60°C (140°F).

Dow Corning[®] 255 Curing Agent should be stirred prior to use because some settling may occur during shipping and storage. The curing agent is reactive with atmospheric moisture so care should be exercised to limit exposure to air prior to use.

PREPARING SURFACES

In applications requiring adhesion, priming will be required for the silicone encapsulants. See the Primer Selection Guide for the correct primer to use with a given product. For best results, the primer should be applied in a very thin, uniform coating and then wiped off after application. After application, it should be thoroughly air dried prior to application of the silicone elastomer. Additional instructions for primer usage can be found in the Dow Corning literature, "How To Use *Dow Corning* Primers and Adhesion Promoters" (Form No. 10-366) and in the information sheets specific to the individual primers.

USEFUL TEMPERATURE RANGES

For most uses, silicone elastomers should be operational over a temperature range of -45 to 200°C (-49 to 392°F) for long periods of time. However, at both the low and high temperature ends of the spectrum, behavior of the materials and performance in particular applications can become more complex and require additional considerations.

For low-temperature performance, thermal cycling to conditions such as -55°C (-67°F) may be possible, but performance should be verified for your parts or assemblies. Factors that may influence performance are configuration and stress sensitivity of components, cooling rates and hold times, and prior temperature history. There are specialized products including *Dow Corning*[®] 3-6121 Encapsulating Elastomer that can perform at -65°C (-85°F) and below.

At the high-temperature end, the durability of the cured silicone elastomer is time and temperature dependent. As expected, the higher the temperature, the shorter the time the material will remain usable.

COMPATIBILITY

Certain materials, chemicals, curing agents and plasticizers can inhibit the cure of *Dow Corning* silicone encapsulants. Most notable of these include:

- Organotin and other organometallic compounds
- Silicone rubber containing organotin catalyst
- Sulfur, polysulfides, polysulfones or other sulfur-containing materials
- · Amines, urethanes or amine-containing materials
- Unsaturated hydrocarbon plasticizers
- Some solder flux residues

If a substrate or material is questionable with respect to potentially causing inhibition of cure, it is recommended that a small scale compatibility test be run to ascertain suitability in a given application. The presence of liquid or uncured product at the interface between the questionable substrate and the cured gel indicates incompatibility and inhibition of cure.

Dow Corning 255 Elastomer is not subject to these inhibition concerns but may experience reversion in sealed applications at high temperature and pressure.

REPAIRABILITY

In the manufacture of electrical/electronic devices it is often desirable to salvage or reclaim damaged or defective units. With most non-silicone rigid potting/encapsulating materials, removal or entry is difficult or impossible without causing excessive damage to internal circuitry. *Dow Corning* silicone encapsulants can be selectively removed with relative ease, any repairs or changes accomplished, and the repaired area repotted in place with additional product.

To remove silicone elastomers, simply cut with a sharp blade or knife and tear and remove unwanted material from the area to be repaired. Sections of the adhered elastomer are best removed from substrates and circuitry by mechanical action such as scraping or rubbing and can be assisted by applying *Dow Corning*[®] brand OS Fluids.

Before applying additional encapsulant to a repaired device, roughen the exposed surfaces of the cured encapsulant with an abrasive paper and rinse with a suitable solvent. This will enhance adhesion and permit the repaired material to become an integral matrix with the existing encapsulant. Silicone prime coats are not recommended for adhering products to themselves.

HANDLING PRECAUTIONS

Dow Corning 255 Elastomer curing agent and uncured catalyzed material will burn skin and eyes upon prolonged contact. In case of eye contact, flush with copious amounts of water for at least 15 minutes and seek medical attention at once. Skin contact areas should be washed with soap and water. Persistent irritation should receive medical attention. Use only with adequate ventilation; if not available, use respiratory protection.

PRODUCT SAFETY INFORMATION REQUIRED FOR SAFE USE IS NOT INCLUDED IN THIS DOCUMENT. BEFORE HANDLING, READ PRODUCT AND MATERIAL SAFETY DATA SHEETS AND CONTAINER LABELS FOR SAFE USE, PHYSICAL AND HEALTH HAZARD INFORMATION. THE MATERIAL SAFETY DATA SHEET IS AVAILABLE ON THE DOW CORNING WEBSITE AT WWW.DOWCORNING.COM, OR FROM YOUR DOW CORNING REPRESENTATIVE, OR DISTRIBUTOR, OR BY CALLING YOUR GLOBAL DOW CORNING CONNECTION.

USABLE LIFE AND STORAGE

Shelf life is indicated by the "Use By" date found on the product label.

For best results, Dow Corning silicone encapsulants should be stored at or below 25°C (77°F). Special precautions must be taken to prevent moisture from contacting these materials. Containers should be kept tightly closed and head or air space minimized. Partially filled containers should be purged with dry air or other gases, such as nitrogen.

Dow Corning 255 Elastomer should be kept refrigerated (10°C/50°F) until use. Any special storage and handling instructions will be printed on the product containers.

PACKAGING

In general, *Dow Corning* silicone 1:1 mix ratio encapsulants are supplied in nominal 0.45-, 3.6-, 18- and 200-kg (1-, 8-, 40- and 440-lb) containers, net weight. *Dow Corning* silicone 10:1 mix ratio encapsulants are supplied in nominal 0.5-, 5-, 25- and 225-kg (1.1-, 11-, 55- and 495-lb) containers, net weight. Packaging options may vary by product. Consult Dow Corning Customer Service at (989) 496-6000 for additional packaging options.

LIMITATIONS

These products are neither tested nor represented as suitable for medical or pharmaceutical uses.

HEALTH AND ENVIRONMENTAL INFORMATION

To support customers in their product safety needs, Dow Corning has an extensive Product Stewardship organization and a team of Product Safety and Regulatory Compliance (PS&RC) specialists available in each area.

For further information, please see our website, www.dowcorning.com, or consult your local Dow Corning representative.

LIMITED WARRANTY INFORMATION – PLEASE READ CAREFULLY

The information contained herein is offered in good faith and is believed to be accurate. However, because conditions and methods of use of our products are beyond our control, this information should not be used in substitution for customer's tests to ensure that Dow Corning's products are safe, effective, and fully satisfactory for the intended end use. Suggestions of use shall not be taken as inducements to infringe any patent.

Dow Corning's sole warranty is that the product will meet the Dow Corning sales specifications in effect at the time of shipment.

Your exclusive remedy for breach of such warranty is limited to refund of purchase price or replacement of any product shown to be other than as warranted.

DOW CORNING SPECIFICALLY DISCLAIMS ANY OTHER EXPRESS OR IMPLIED WARRANTY OF FITNESS FOR A PARTICULAR PURPOSE OR MERCHANTABILITY.

DOW CORNING DISCLAIMS LIABILITY FOR ANY INCIDENTAL OR CONSEQUENTIAL DAMAGES.



Electronics Solutions